

MATERIAL DECLARATION SHEET



Material Number	CDDFN2-T5.0C			
Product Line	Diode Products			
Compliance Date	16 Jun 2009			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FR-4 Board	Substrate/ Terminal	0.000223	Copper	7440-50-8	43.01%	43.01%	29.00
				Nickel	7440-02-0	3.677%	3.677%	
				Gold	7440-57-5	0.099%	0.099%	
				Epoxy Resin	-----	53.22%	53.22%	
2	Wafer	Diode	0.000029	Silicon	7440-21-3	90.70%	90.70%	3.77
				Aluminum	7429-90-5	1.90%	1.90%	
				Titanium	7440-32-6	0.001%	0.001%	
				Gold	7440-57-5	6.40%	6.40%	
				Arsenic	7440-38-2	0.07%	0.07%	
3	Al wire	Conductor	0.000001	Aluminum	7429-90-5	>99%	>99%	0.13
				Silicon	7440-21-3	<1%	<1%	
4	Silver paste	Welding	0.000005	Additives	-----	1~7%	1~7%	0.65
				Silver	7440-22-4	76~85%	76~85%	
				Epoxy resins	-----	5~25%	5~25%	
5	Molding Compound	Outer	0.000511	Silica Fused	60676-86-0	70~90%	70~90%	66.45
				Epoxy Resin	-----	5~15%	5~15%	
				Phenol Resin	-----	5~15%	5~15%	
				Carbon Black	1333-86-4	0.1~0.5%	0.1~0.5%	
				Catalyst	-----	<1%	<1%	
Total weight			0.000769					

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This Document was updated on: 21 Aug 2009

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.